BS EN IEC 61760-1:2020

BSI Standards Publication

Surface mounting technology

Part 1: Standard method for the specification of surface mounting components (SMDs)

bsi.

National foreword

This British Standard is the UK implementation of EN IEC 61760-1:2020. It is identical to IEC 61760-1:2020. It supersedes BS EN 61760-1:2006, which is withdrawn.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its committee manager.

This publication does not purport to include all the necessary provisions of a contract. Users are responsible for its correct application.

Published by BSI Standards Limited 2020

ISBN 978 0 580 99144 8

ICS 31.020; 31.240

Compliance with a British Standard cannot confer immunity from legal obligations.

This British Standard was published under the authority of the Standards Policy and Strategy Committee on 30 September 2020.

Amendments/corrigenda issued since publication

Date	Text affected

EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN IEC 61760-1

September 2020

ICS 31.240

Supersedes EN 61760-1:2006 and all of its amendments and corrigenda (if any)

English Version

Surface mounting technology - Part 1: Standard method for the specification of surface mounting components (SMDs) (IEC 61760-1:2020)

Technique du montage en surface - Partie 1: Méthode normalisée pour la spécification des composants montés en surface (CMS)
(IEC 61760-1:2020)

Oberflächenmontagetechnik - Teil 1: Genormtes Verfahren zur Spezifizierung oberflächenmontierbarer Bauelemente (SMDs)
(IEC 61760-1:2020)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

European foreword

The text of document 91/1648/FDIS, future edition 3 of IEC 61760-1, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61760-1:2020.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2021-05-18
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2023-08-18

This document supersedes EN 61760-1:2006 and all of its amendments and corrigenda (if any).

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC shall not be held responsible for identifying any or all such patent rights.

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The text of the International Standard IEC 61760-1:2020 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60062	NOTE	Harmonized as EN 60062
IEC 60068-1	NOTE	Harmonized as EN 60068-1
IEC 60068-2-20	NOTE	Harmonized as EN 60068-2-20
IEC 60068-2-69	NOTE	Harmonized as EN 60068-2-69
IEC 60191-6-19	NOTE	Harmonized as EN 60191-6-19
IEC 60352-5	NOTE	Harmonized as EN 60352-5
IEC 60749 (series)	NOTE	Harmonized as EN 60749 (series)
IEC 61188-5-1	NOTE	Harmonized as EN 61188-5-1
IEC 61189-5-504	NOTE	Harmonized as EN IEC 61189-5-504
IEC 62474	NOTE	Harmonized as EN IEC 62474

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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SURFACE MOUNTING TECHNOLOGY –

Part 1: Standard method for the specification of surface mounting components (SMDs)

FOREWORD

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International Standard IEC 61760-1 has been prepared by IEC technical committee 91: Surface mounting technology.

This third edition cancels and replaces the second edition published in 2006. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) inclusion of additional mounting methods: conductive glue bonding, sintering and solderless interconnection.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
91/1648/FDIS	91/1653/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61760 series, published under the general title *Surface mounting technology*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

Specifications for electronic components have in the past been formulated for each component family. The regulations for environmental tests have been selected from IEC 60068 and other IEC and ISO publications. The intention for this procedure was that all components, once installed in a piece of equipment, had to satisfy certain criteria.

The introduction and increasing use of different mounting processes on one assembly make it necessary to extend the existing requirements to include those arising from processing during assembly.

Nevertheless, there existed no harmonized standard that prescribes the content of a component specification before the publication of IEC 61760-1. It is the purpose of this document to define the general requirements for component specifications derived from the assembly processes. This is done in three steps.

In the first step, general requirements for component specifications and component design related to the handling and placement of the component on the substrate are given (Clause 4). In the second step, the requirements related to assembly processes are given (Clause 5). In the third step, additional requirements resulting from specific mounting methods are given (Clauses 6 to 9).

Mixed technology boards, i.e. boards containing through-hole components and SMDs, require additional consideration with respect to the through-hole components. These may be subject to the same requirements as the SMDs. Persons responsible for drafting specifications for "non-surface mounting components" wishing to include a statement on their ability to withstand surface mounting conditions should use the classifications and tests set out in the present document.

SURFACE MOUNTING TECHNOLOGY –

Part 1: Standard method for the specification of surface mounting components (SMDs)

1 Scope

This part of IEC 61760 defines requirements for component specifications of electronic components that are intended for usage in surface mounting technology. To this end, it specifies a reference set of process conditions and related test conditions to be considered when compiling component specifications.

The objective of this document is to ensure that a wide variety of SMDs can be subjected to the same placement, mounting and subsequent processes (e.g. cleaning, inspection) during assembly. This document defines tests and requirements that need to be part of any SMD component's general, sectional or detail specification. In addition, this document provides component users and manufacturers with a reference set of typical process conditions used in surface mounting technology.

Some of the requirements for component specifications in this document are also applicable to components with leads intended for mounting on a circuit board. Cases for which this is appropriate are indicated in the relevant subclauses.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068 (all parts), *Environmental testing*

IEC 60068-2-2, *Environmental testing – Part 2-2: Tests – Test B: Dry heat*

IEC 60068-2-21, *Environmental testing – Part 2-21: Tests – Test U: Robustness of terminations and integral mounting devices*

IEC 60068-2-45:1980, *Basic environmental testing procedures – Part 2-45: Tests – Test XA and guidance: Immersion in cleaning solvents*
IEC 60068-2-45:1980/AMD1:1993

IEC 60068-2-58, *Environmental testing – Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMDs)*

IEC 60191-6, *Mechanical standardization of semiconductor devices – Part 6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages*

IEC 60194-2, *Printed boards design, manufacture and assembly – Vocabulary – Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies*